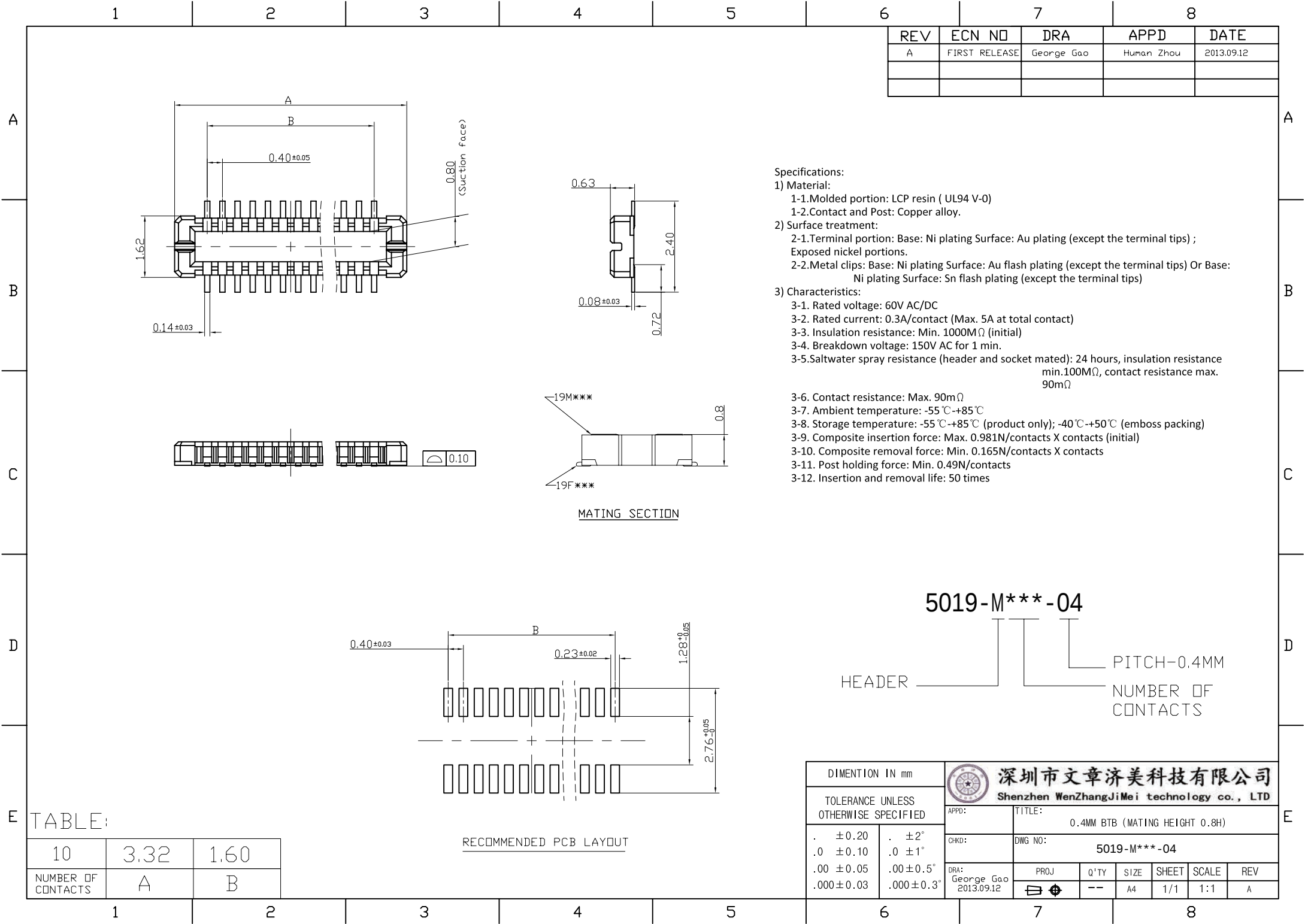




REV	ECN NO	DRA	APPD	DATE
A	FIRST RELEASE	George Gao	Human Zhou	2013.09.12

Specifications:

1) Material:

1-1.Molded portion: LCP resin (UL94 V-0)

1-2.Contact and Post: Copper alloy.

2) Surface treatment:

2-1.Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) ; Exposed nickel portions.

2-2.Metal clips: Base: Ni plating Surface: Au flash plating (except the terminal tips) Or Base: Ni plating Surface: Sn flash plating (except the terminal tips)

3) Characteristics:

3-1. Rated voltage: 60V AC/DC

3-2. Rated current: 0.3A/contact (Max. 5A at total contact)

3-3. Insulation resistance: Min. 1000MΩ (initial)

3-4. Breakdown voltage: 150V AC for 1 min.

3-5.Saltwater spray resistance (header and socket mated): 24 hours, insulation resistance min.100MΩ, contact resistance max. 90mΩ

3-6. Contact resistance: Max. 90mΩ

3-7. Ambient temperature: -55℃~+85℃

3-8. Storage temperature: -55℃~+85℃ (product only); -40℃~+50℃ (emboss packing)

3-9. Composite insertion force: Max. 0.981N/contacts X contacts (initial)

3-10. Composite removal force: Min. 0.165N/contacts X contacts

3-11. Post holding force: Min. 0.49N/contacts

3-12. Insertion and removal life: 50 times

5019-M***-04

HEADER

PITCH=0.4MM

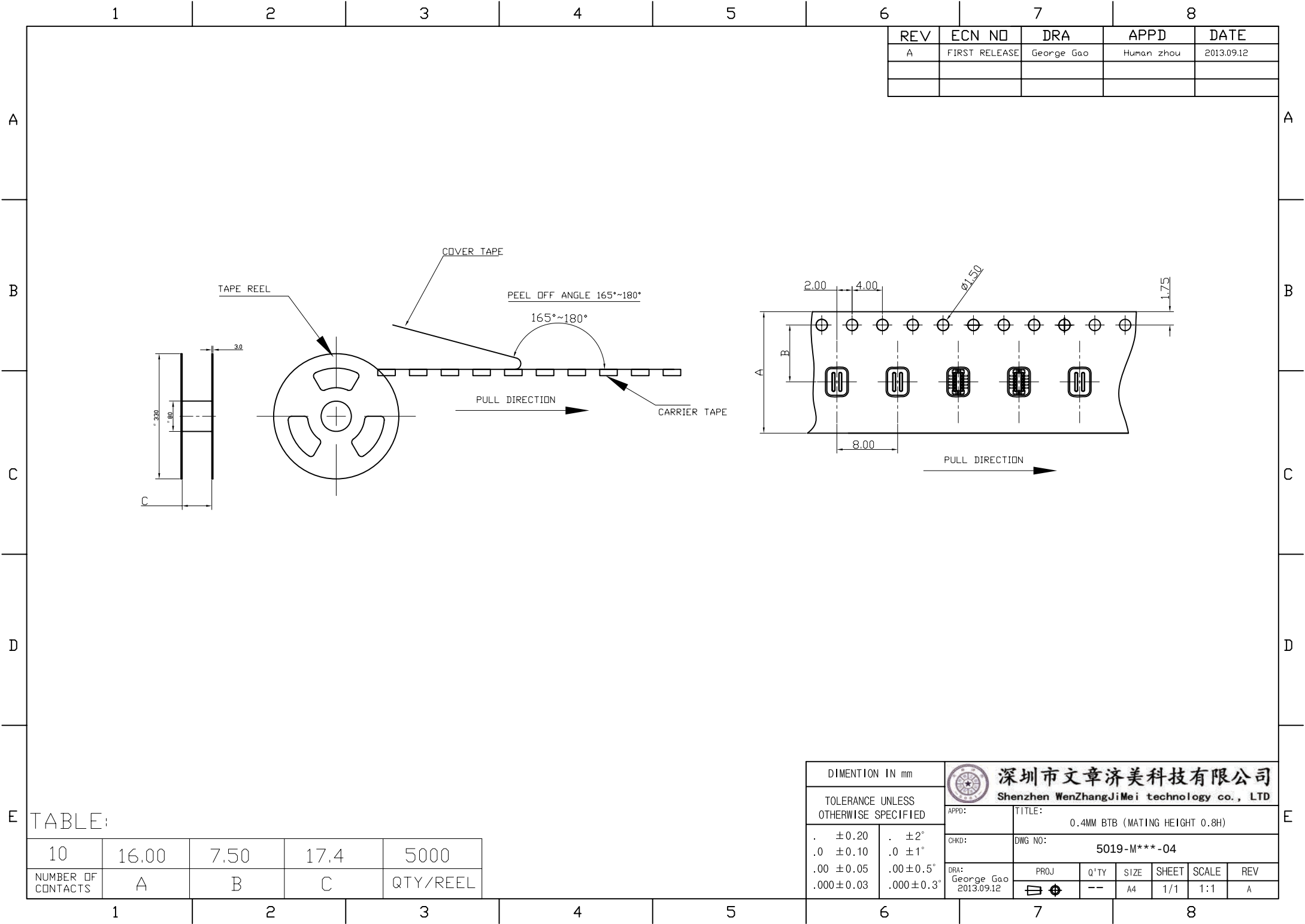
NUMBER OF CONTACTS

TABLE:

10	3.32	1.60
NUMBER OF CONTACTS	A	B

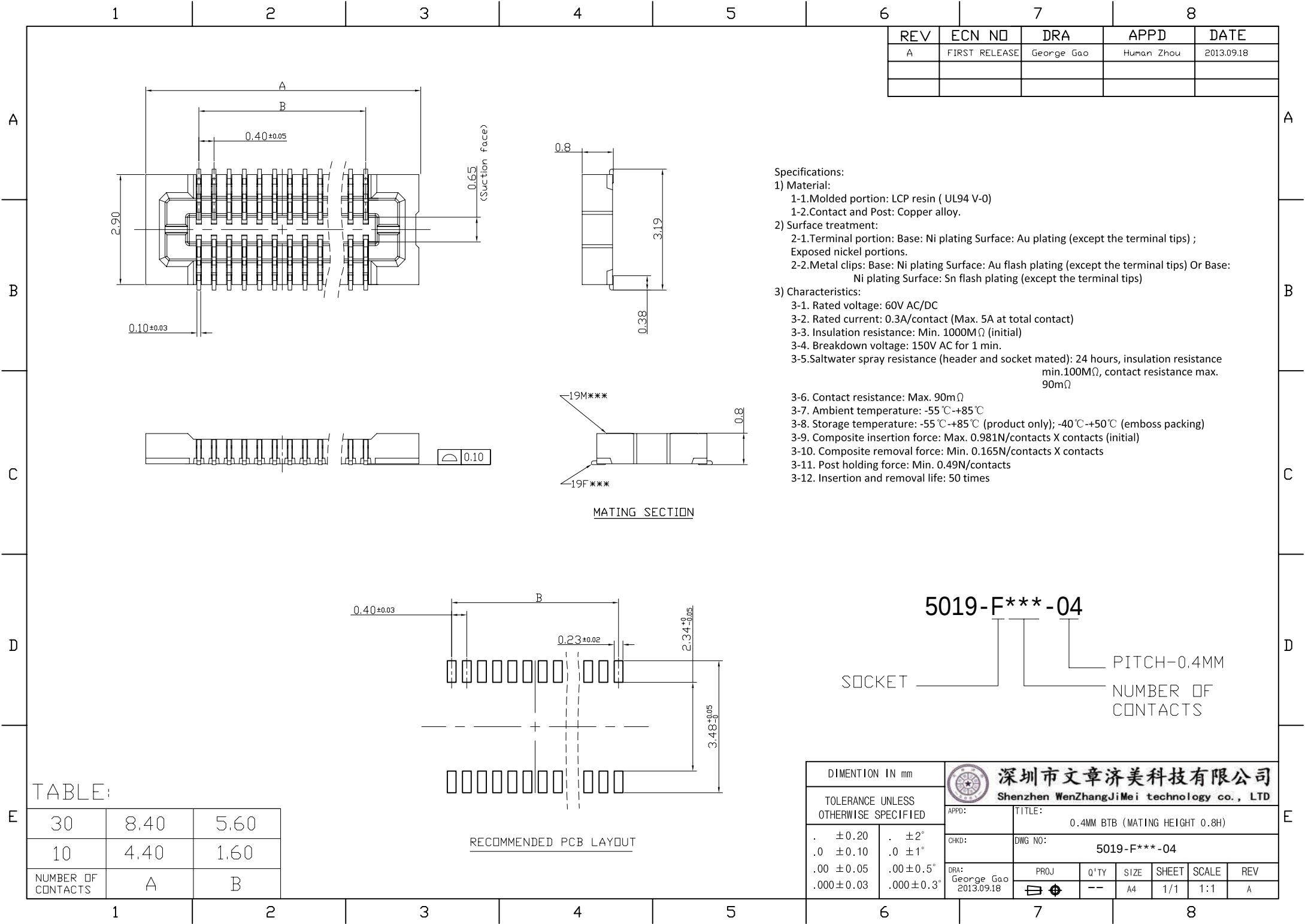
RECOMMENDED PCB LAYOUT

DIMENTION IN mm		深圳市文章济美科技有限公司 Shenzhen WenZhangJiMei technology co., LTD					
TOLERANCE UNLESS OTHERWISE SPECIFIED		APPD:	TITLE: 0.4MM BTB (MATING HEIGHT 0.8H)				
. ±0.20 .0 ±0.10 .00 ±0.05 .000 ±0.03		CHKD:	DWG NO: 5019-M***-04				
. ±2° .0 ±1° .00 ±0.5° .000 ±0.3°		DRA: George Gao 2013.09.12	PROJ	Q'TY	SIZE	SHEET	SCALE
			1/1	1/1	1/1	1/1	1/1
			1/1	1/1	1/1	1/1	1/1



REV	ECN NO	DRA	APPD	DATE
A	FIRST RELEASE	George Gao	Human zhou	2013.09.12

E	TABLE:					OTHERWISE SPECIFIED		APPD:	TITLE: 0.4MM BTB (MATING HEIGHT 0.8H)						E
	10	16.00	7.50	17.4	5000	. ±0.20 .0 ±0.10 .00 ±0.05 .000±0.03	. ±2° .0 ±1° .00±0.5° .000±0.3°	CHKD:	DWG NO: 5019-M***-04						
	NUMBER OF CONTACTS	A	B	C	QTY/REEL			DRA: George Gao 2013.09.12	PROJ	Q'TY	SIZE	SHEET	SCALE	REV	
								深圳市文章济美科技有限公司 Shenzhen WenZhangJiMei technology co., LTD		--	A4	1/1	1:1	A	
1		2		3		4		5		6		7		8	



REV	ECN NO	DRA	APPD	DATE
A	FIRST RELEASE	George Gao	Human Zhou	2013.09.18

Specifications:

1) Material:

1-1.Molded portion: LCP resin (UL94 V-0)

1-2.Contact and Post: Copper alloy.

2) Surface treatment:

2-1.Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) ; Exposed nickel portions.

2-2.Metal clips: Base: Ni plating Surface: Au flash plating (except the terminal tips) Or Base: Ni plating Surface: Sn flash plating (except the terminal tips)

3) Characteristics:

3-1. Rated voltage: 60V AC/DC

3-2. Rated current: 0.3A/contact (Max. 5A at total contact)

3-3. Insulation resistance: Min. 1000MΩ (initial)

3-4. Breakdown voltage: 150V AC for 1 min.

3-5.Saltwater spray resistance (header and socket mated): 24 hours, insulation resistance min.100MΩ, contact resistance max. 90mΩ

3-6. Contact resistance: Max. 90mΩ

3-7. Ambient temperature: -55℃~+85℃

3-8. Storage temperature: -55℃~+85℃ (product only); -40℃~+50℃ (emboss packing)

3-9. Composite insertion force: Max. 0.981N/contacts X contacts (initial)

3-10. Composite removal force: Min. 0.165N/contacts X contacts

3-11. Post holding force: Min. 0.49N/contacts

3-12. Insertion and removal life: 50 times

5019-F***-04

SOCKET

PITCH-0.4MM

NUMBER OF CONTACTS

TABLE:

30	8.40	5.60
10	4.40	1.60
NUMBER OF CONTACTS	A	B

DIMENTION IN mm		深圳市文章济美科技有限公司 Shenzhen WenZhangJiMei technology co., LTD					
TOLERANCE UNLESS OTHERWISE SPECIFIED		APPD:	TITLE: 0.4MM BTB (MATING HEIGHT 0.8H)				
. ±0.20 .0 ±0.10 .00 ±0.05 .000 ±0.03		CHKD:	DWG NO: 5019-F***-04				
. ±2° .0 ±1° .00 ±0.5° .000 ±0.3°		DRA: George Gao 2013.09.18	PROJ	Q'TY	SIZE	SHEET	SCALE
			1/1	1/1	1/1	1/1	1/1
			1/1	1/1	1/1	1/1	1/1

